Title (en)

Connector for leadless IC package

Title (de)

Verbinder für leitungslose integrierte Schaltungspackung

Title (fr)

Connecteur de circuit integré sans fil

Publication

EP 0503810 B1 19960717 (EN)

Application

EP 92301753 A 19920302

Priority

JP 7586491 A 19910315

Abstract (en)

[origin: EP0503810A2] A connector for a leadless IC package having contacts to be pressure contacted conductive pads arranged on a lower surface of a leadless IC, wherein each of the contacts is formed of a spring element, the connector including a contact holding portion in which the spring element is implanted, a contact braking portion disposed above the contact holding portion, and a contact operating portion laterally movably disposed between the contact braking portion and the contact holding portion, the spring element being permitted to penetrate a contact operating through-hole formed in the operating portion, a distal end of the spring element being received in a contact braking through-hole formed in the braking portion, the spring element being sidewardly pressurized by an inner wall of the contact operating through-hole when the operating portion is moved in one direction, so that the spring element would be bent and displaced, the spring element being restored to its original state when the operating portion is laterally moved in the other direction, the distal end portion of the spring element being expanded and contracted while it is braked by the inner wall of the contact braking through-hole by the bending displacement and restoration, the distal end portion of the spring element being pressure contacted the conductive pad of the IC when the spring element is expanded. <IMAGE>

IPC 1-7

H05K 7/10; H01R 23/72

IPC 8 full level

H01L 23/32 (2006.01); **H01R 11/18** (2006.01); **H01R 24/00** (2006.01); **H01R 33/76** (2006.01); **H05K 7/10** (2006.01); G01R 1/073 (2006.01)

CPC (source: EP KR US)

H01R 9/00 (2013.01 - KR); **H01R 12/714** (2013.01 - EP US); **H05K 7/1069** (2013.01 - EP US); G01R 1/07357 (2013.01 - EP US)

Cited by

EP0658959A3; EP4075149A3; GB2290176B

Designated contracting state (EPC)

DE FR GB IT

DOCDB simple family (publication)

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EP 92301753 A 19920302; CA 2062199 A 19920303; DE 69212189 T 19920302; JP 7586491 A 19910315; KR 920003718 A 19920306; MY PI19920375 A 19920309; US 9064493 A 19930713